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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	I ² C, IRSCI, SCI, SPI
Peripherals	LED, LVD, POR, PWM
Number of I/O	30
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	42-SDIP (0.600", 15.24mm)
Supplier Device Package	42-PDIP
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908ap32cbe

Revision History

Date	Revision Level	Description	Page Number(s)
January 2007	4	15.7.2 ADC Clock Control Register — Changed “The ADC clock should be set to between 500kHz and 2MHz” to “The ADC clock should be set to between 500kHz and 1MHz”	254
August 2005	3	Table 22-4 . DC Electrical Characteristics (5V) — Updated V_{OL} values.	299
		Table 22-6 . Oscillator Specifications (5V) and Table 22-10 . Oscillator Specifications (3V) — Corrected internal oscillator clock frequency, f_{CLK} . Updated crystal oscillator component values C_L , C_1 , C_2 , R_B , and R_S .	301, 305
October 2003	2.5	Added MC68HC908AP16/AP8 information throughout.	—
		Section 10. Monitor ROM (MON) — Corrected RAM address to \$60.	167
		Section 24. Electrical Specifications — Added run and wait I_{DD} data for 8MHz at 3V.	421
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July 2003	2.3	Removed MC68HC908AP16 references throughout.	—
		Table 1-2 . Pin Functions — Added footnote for V_{REG} .	30
		5.3 Configuration Register 1 (CONFIG1) — Clarified LVIPWRD and LVIREGD bits.	67
		Section 8. Clock Generator Module (CGM) , 8.7.2 Stop Mode — Updated BSC bit behavior.	125
		10.5 ROM-Resident Routines — Corrected data size limits and control byte size for EE_READ and EE_WRITE.	168–193
		Figure 12-2 . Timebase Control Register (TBCR) — Corrected register address.	207
		Section 24. Electrical Specifications — Updated.	415
May 2003	2.2	Updated for $f_{NOM} = 125kHz$ and filter components in CGM section.	101
		Updated electricals.	415

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System Integration Module (SIM)

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Table 1-2. Pin Functions

PIN NAME	PIN DESCRIPTION	IN/OUT	VOLTAGE LEVEL
PTB0/SDA PTB1/SCL PTB2/TxD PTB3/RxD PTB4/T1CH0 PTB5/T1CH1 PTB6/T2CH0 PTB7/T2CH1	8-bit general purpose I/O port; PTB0–PTB3 are open drain when configured as output. PTB4–PTB7 have schmitt trigger inputs.	In/Out	V_{DD}
	PTB0 as SDA of MMIIC.	In/Out	V_{DD}
	PTB1 as SCL of MMIIC.	In/Out	V_{DD}
	PTB2 as TxD of SCI; open drain output.	Out	V_{DD}
	PTB3 as RxD of SCI.	In	V_{DD}
	PTB4 as T1CH0 of TIM1.	In/Out	V_{DD}
	PTB5 as T1CH1 of TIM1.	In/Out	V_{DD}
	PTB6 as T2CH0 of TIM2.	In/Out	V_{DD}
	PTB7 as T2CH1 of TIM2.	In/Out	V_{DD}
PTC0/ $\overline{\text{IRQ2}}$ PTC1 PTC2/MISO PTC3/MOSI PTC4/ $\overline{\text{SS}}$ PTC5/SPSCK PTC6/SCTxD PTC7/SCRxD	8-bit general purpose I/O port; PTC6 and PTC7 are open drain when configured as output.	In/Out	V_{DD}
	PTC0 is shared with $\overline{\text{IRQ2}}$ and has schmitt trigger input.	In	V_{DD}
	PTC2 as MISO of SPI.	In	V_{DD}
	PTC3 as MOSI of SPI.	Out	V_{DD}
	PTC4 as $\overline{\text{SS}}$ of SPI.	In	V_{DD}
	PTC5 as SPSCK of SPI.	In/Out	V_{DD}
	PTC6 as SCTxD of IRSCI; open drain output.	Out	V_{DD}
	PTC7 as SCRxD of IRSCI.	In	V_{DD}
PTD0/KBI0 : PTD7/KBI7	8-bit general purpose I/O port with schmitt trigger inputs.	In/Out	V_{DD}
	Pins as keyboard interrupts (with pullup), KBI0–KBI7.	In	V_{DD}

1. See Chapter 22 Electrical Specifications for V_{REG} tolerance.

1.6 Power Supply Bypassing (V_{DD} , V_{DDA} , V_{SS} , V_{SSA})

V_{DD} and V_{SS} are the power supply and ground pins, the MCU operates from a single power supply together with an on chip voltage regulator.

Fast signal transitions on MCU pins place high, short-duration current demands on the power supply. To prevent noise problems, take special care to provide power supply bypassing at the MCU as Figure 1-5 shows. Place the bypass capacitors as close to the MCU power pins as possible. Use high-frequency-response ceramic capacitor for C_{BYPASS} , C_{BULK} are optional bulk current bypass capacitors for use in applications that require the port pins to source high current level.



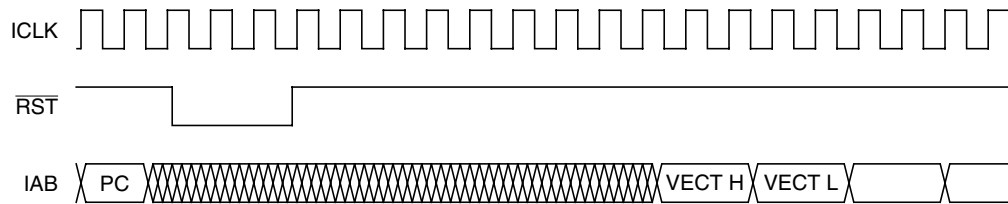


Figure 7-4. External Reset Timing

7.3.2 Active Resets from Internal Sources

All internal reset sources actively pull the \overline{RST} pin low for 32 ICLK cycles to allow resetting of external peripherals. The internal reset signal \overline{IRST} continues to be asserted for an additional 32 cycles (see Figure 7-5). An internal reset can be caused by an illegal address, illegal opcode, COP timeout, LVI, or POR (see Figure 7-6).

NOTE

For LVI or POR resets, the SIM cycles through 4096 + 32 ICLK cycles during which the SIM forces the \overline{RST} pin low. The internal reset signal then follows the sequence from the falling edge of \overline{RST} shown in Figure 7-5.

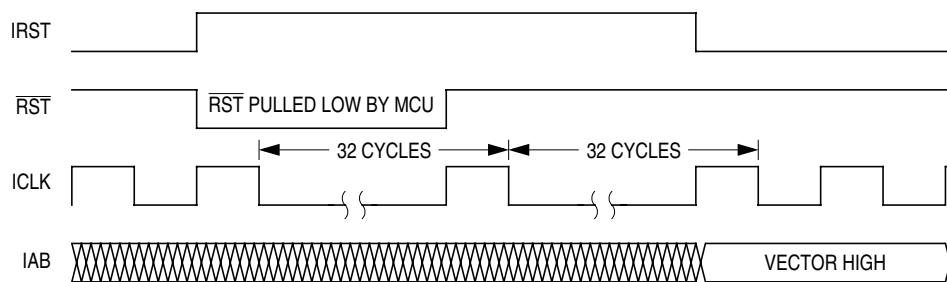


Figure 7-5. Internal Reset Timing

The COP reset is asynchronous to the bus clock.

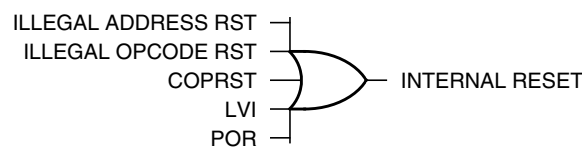


Figure 7-6. Sources of Internal Reset

The active reset feature allows the part to issue a reset to peripherals and other chips within a system built around the MCU.

7.3.2.1 Power-On Reset

When power is first applied to the MCU, the power-on reset module (POR) generates a pulse to indicate that power-on has occurred. The external reset pin (\overline{RST}) is held low while the SIM counter counts out 4096 + 32 ICLK cycles. Thirty-two ICLK cycles later, the CPU and memories are released from reset to allow the reset vector sequence to occur.

Table 7-3. Interrupt Sources

Priority	INT Flag	Vector Address	Interrupt Source
<div> <div>Lowest</div> <div>↑</div> <div>↓</div> <div>Highest</div> </div>	—	\$FFD0	Reserved
		\$FFD1	
	IF21	\$FFD2	Timebase
		\$FFD3	
	IF20	\$FFD4	Infrared SCI Transmit
		\$FFD5	
	IF19	\$FFD6	Infrared SCI Receive
		\$FFD7	
	IF18	\$FFD8	Infrared SCI Error
		\$FFD9	
	IF17	\$FFDA	SPI Transmit
		\$FFDB	
	IF16	\$FFDC	SPI Receive
		\$FFDD	
	IF15	\$FFDE	ADC Conversion Complete
		\$FFDF	
	IF14	\$FFE0	Keyboard
		\$FFE1	
	IF13	\$FFE2	SCI Transmit
		\$FFE3	
	IF12	\$FFE4	SCI Receive
		\$FFE5	
	IF11	\$FFE6	SCI Error
		\$FFE7	
	IF10	\$FFE8	MMIIC
		\$FFE9	
	IF9	\$FFEA	TIM2 Overflow
		\$FFEB	
	IF8	\$FFEC	TIM2 Channel 1
		\$FFED	
	IF7	\$FFEE	TIM2 Channel 0
		\$FFEF	
	IF6	\$FFF0	TIM1 Overflow
		\$FFF1	
	IF5	\$FFF2	TIM1 Channel 1
		\$FFF3	
	IF4	\$FFF4	TIM1 Channel 0
		\$FFF5	
	IF3	\$FFF6	PLL
		\$FFF7	
	IF2	\$FFF8	IRQ2
		\$FFF9	
	IF1	\$FFFA	IRQ1
		\$FFFB	
	—	\$FFFC	SWI
		\$FFFD	
	—	\$FFFE	Reset
		\$FFFF	

8.5.6 EE_WRITE

EE_WRITE is used to write a set of data from the data array to FLASH.

Table 8-16. EE_WRITE Routine

Routine Name	EE_WRITE
Routine Description	Emulated EEPROM write. Data size ranges from 7 to 15 bytes at a time.
Calling Address	\$FF36
Stack Used	30 bytes
Data Block Format	Bus speed (BUS_SPD) Data size (DATASIZE) ⁽¹⁾ Starting address (ADDRH) ⁽²⁾ Starting address (ADDRL) ⁽¹⁾ Data 1 : Data N

1. The minimum data size is 7 bytes. The maximum data size is 15 bytes.
2. The start address must be a page boundary start address.

The start location of the FLASH to be programmed is specified by the address ADDRH:ADDRL and the number of bytes in the data array is specified by DATASIZE. The minimum number of bytes that can be programmed in one routine call is 7 bytes, the maximum is 15 bytes. ADDRH:ADDRL must always be the start of boundary address (the page start address: \$X000, \$X200, \$X400, \$X600, \$X800, \$XA00, \$XC00, or \$XE00) and DATASIZE must be the same size when accessing the same page.

In some applications, the user may want to repeatedly store and read a set of data from an area of non-volatile memory. This is easily possible when using an EEPROM array. As the write and erase operations can be executed on a byte basis. For FLASH memory, the minimum erase size is the page — 512 bytes per page for MC68HC908AP64. If the data array size is less than the page size, writing and erasing to the same page cannot fully utilize the page. Unused locations in the page will be wasted. The EE_WRITE routine is designed to emulate the properties similar to the EEPROM. Allowing a more efficient use of the FLASH page for data storage.

When the user dedicates a page of FLASH for data storage, and the size of the data array defined, each call of the EE_WRITE routine will automatically transfer the data in the data array (in RAM) to the next blank block of locations in the FLASH page. Once a page is filled up, the EE_WRITE routine automatically erases the page, and starts reuse the page again. In the 512-byte page, an 9-byte control block is used by the routine to monitor the utilization of the page. In effect, only 503 bytes are used for data storage. (see Figure 8-10). The page control operations are transparent to the user.

When using this routine to store a 8-byte data array, the FLASH page can be programmed 62 times before the an erase is required. In effect, the write/erase endurance is increased by 62 times. When a 15-byte data array is used, the write/erase endurance is increased by 33 times. Due to the FLASH page size limitation, the data array is limited from 7 bytes to 15 bytes.

Address: T1CH0H, \$0026 and T2CH0H, \$0031

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 15	14	13	12	11	10	9	Bit 8
Write:								
Reset:	Indeterminate after reset							

Figure 9-12. TIM Channel 0 Register High (TCH0H)

Address: T1CH0L, \$0027 and T2CH0L, \$0032

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 7	6	5	4	3	2	1	Bit 0
Write:								
Reset:	Indeterminate after reset							

Figure 9-13. TIM Channel 0 Register Low (TCH0L)

Address: T1CH1H, \$0029 and T2CH1H, \$0034

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 15	14	13	12	11	10	9	Bit 8
Write:								
Reset:	Indeterminate after reset							

Figure 9-14. TIM Channel 1 Register High (TCH1H)

Address: T1CH1L, \$002A and T2CH1L, \$0035

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 7	6	5	4	3	2	1	Bit 0
Write:								
Reset:	Indeterminate after reset							

Figure 9-15. TIM Channel 1 Register Low (TCH1L)

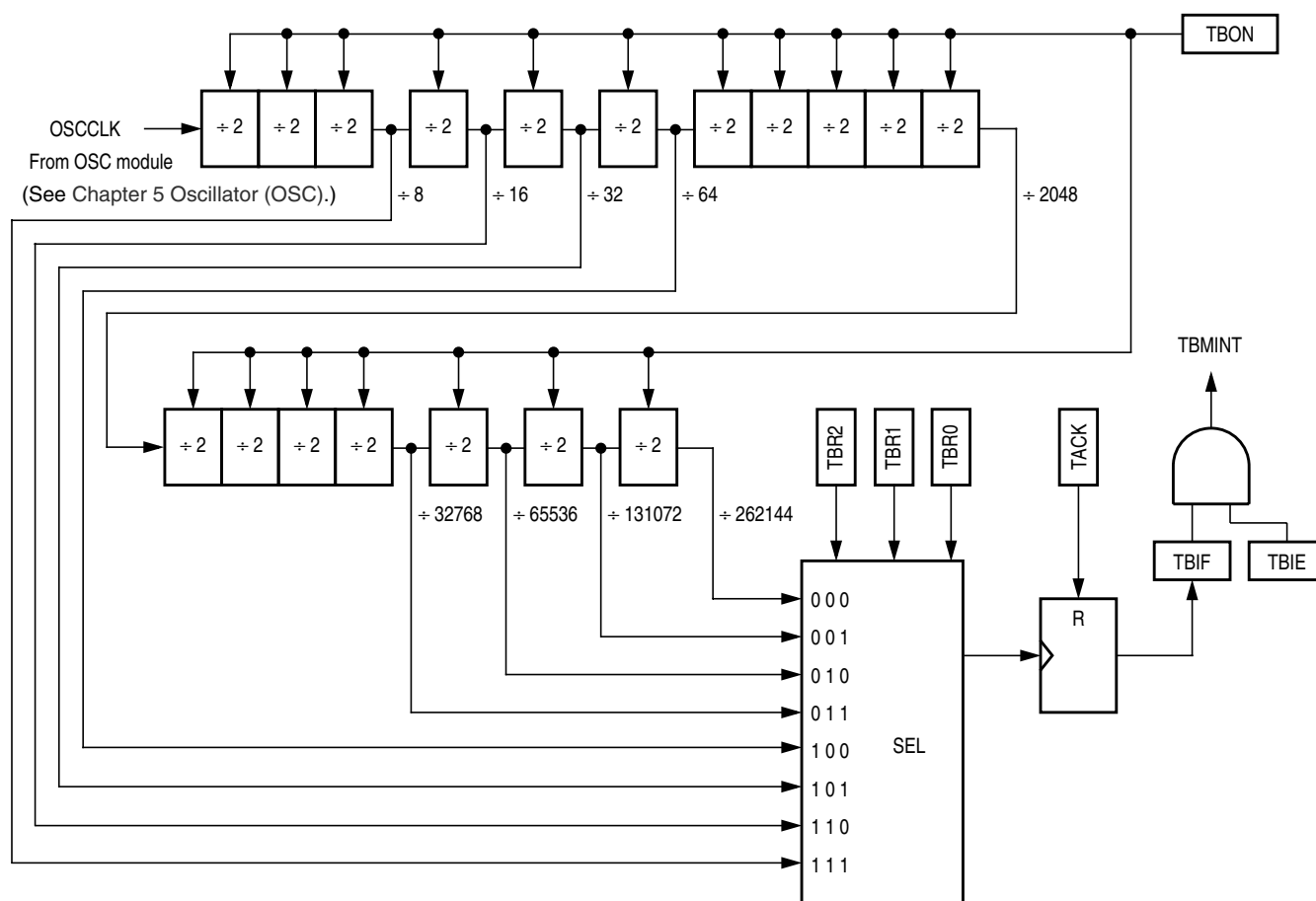


Figure 10-1. Timebase Block Diagram

10.4 Timebase Register Description

The timebase has one register, the TBCR, which is used to enable the timebase interrupts and set the rate.

Address: \$0051

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	TBIF	TBR2	TBR1	TBR0	0	TBIE	TBON	R
Write:					TACK			
Reset:	0	0	0	0	0	0	0	0

= Unimplemented
 R = Reserved

Figure 10-2. Timebase Control Register (TBCR)

TBIF — Timebase Interrupt Flag

This read-only flag bit is set when the timebase counter has rolled over.

1 = Timebase interrupt pending

0 = Timebase interrupt not pending

Depending on the state of the WAKE bit in SCC1, either of two conditions on the RxD pin can bring the receiver out of the standby state:

- **Address mark** — An address mark is a logic 1 in the most significant bit position of a received character. When the WAKE bit is set, an address mark wakes the receiver from the standby state by clearing the RWU bit. The address mark also sets the SCI receiver full bit, SCRF. Software can then compare the character containing the address mark to the user-defined address of the receiver. If they are the same, the receiver remains awake and processes the characters that follow. If they are not the same, software can set the RWU bit and put the receiver back into the standby state.
- **Idle input line condition** — When the WAKE bit is clear, an idle character on the RxD pin wakes the receiver from the standby state by clearing the RWU bit. The idle character that wakes the receiver does not set the receiver idle bit, IDLE, or the SCI receiver full bit, SCRF. The idle line type bit, ILTY, determines whether the receiver begins counting logic 1s as idle character bits after the start bit or after the stop bit.

NOTE

With the WAKE bit clear, setting the RWU bit after the RxD pin has been idle may cause the receiver to wake up immediately.

11.4.3.7 Receiver Interrupts

The following sources can generate CPU interrupt requests from the SCI receiver:

- **SCI receiver full (SCRF)** — The SCRF bit in SCS1 indicates that the receive shift register has transferred a character to the SCDR. SCRF can generate a receiver CPU interrupt request. Setting the SCI receive interrupt enable bit, SCRIE, in SCC2 enables the SCRF bit to generate receiver CPU interrupts.
- **Idle input (IDLE)** — The IDLE bit in SCS1 indicates that 10 or 11 consecutive logic 1s shifted in from the RxD pin. The idle line interrupt enable bit, ILIE, in SCC2 enables the IDLE bit to generate CPU interrupt requests.

11.4.3.8 Error Interrupts

The following receiver error flags in SCS1 can generate CPU interrupt requests:

- **Receiver overrun (OR)** — The OR bit indicates that the receive shift register shifted in a new character before the previous character was read from the SCDR. The previous character remains in the SCDR, and the new character is lost. The overrun interrupt enable bit, ORIE, in SCC3 enables OR to generate SCI error CPU interrupt requests.
- **Noise flag (NF)** — The NF bit is set when the SCI detects noise on incoming data or break characters, including start, data, and stop bits. The noise error interrupt enable bit, NEIE, in SCC3 enables NF to generate SCI error CPU interrupt requests.
- **Framing error (FE)** — The FE bit in SCS1 is set when a logic 0 occurs where the receiver expects a stop bit. The framing error interrupt enable bit, FEIE, in SCC3 enables FE to generate SCI error CPU interrupt requests.
- **Parity error (PE)** — The PE bit in SCS1 is set when the SCI detects a parity error in incoming data. The parity error interrupt enable bit, PEIE, in SCC3 enables PE to generate SCI error CPU interrupt requests.

12.5 SCI Functional Description

Figure 12-5 shows the structure of the SCI.

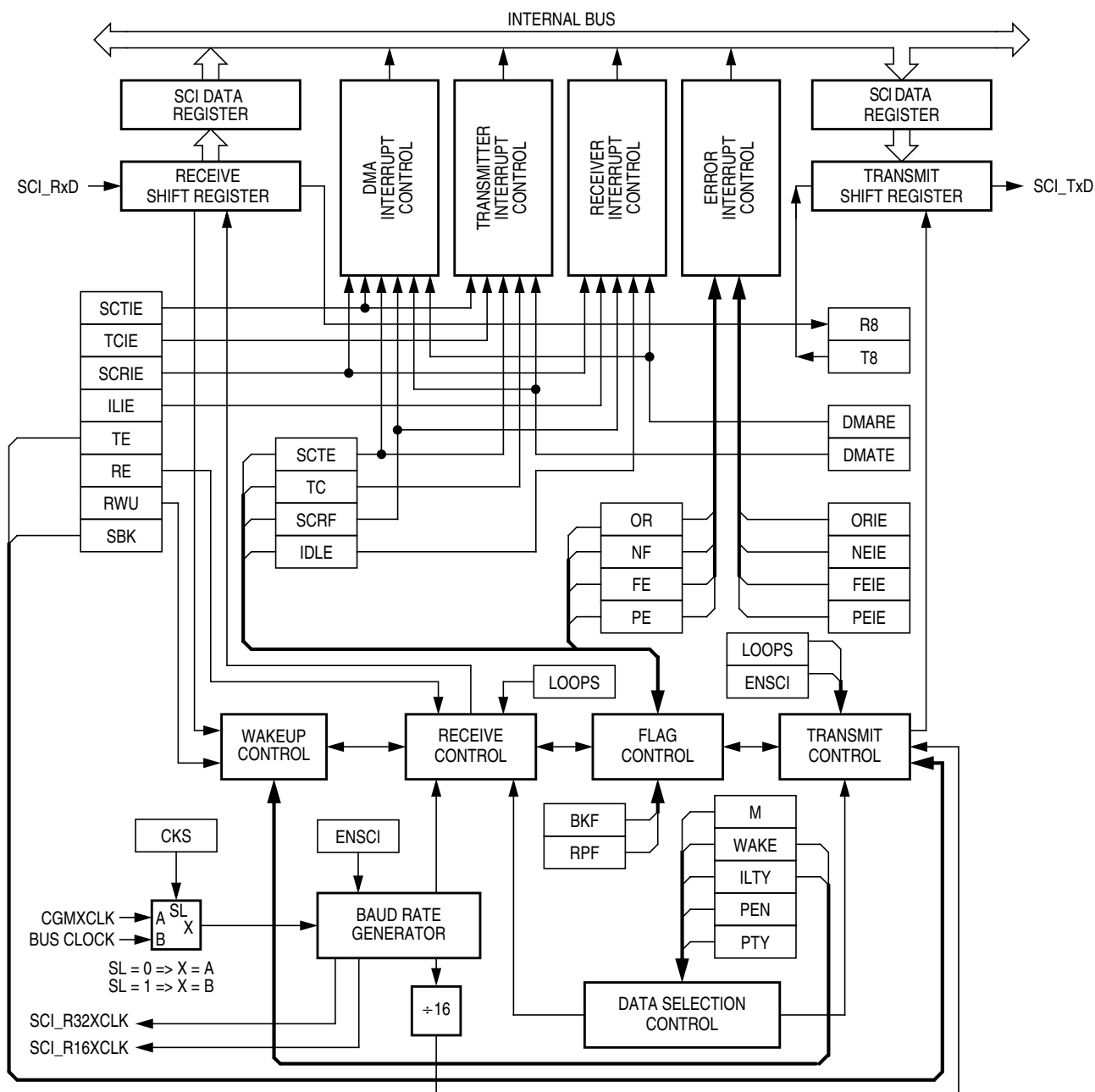


Figure 12-5. SCI Module Block Diagram

12.5.3.2 Character Reception

During an SCI reception, the receive shift register shifts characters in from the RxD pin. The SCI data register (IRSCDR) is the read-only buffer between the internal data bus and the receive shift register.

After a complete character shifts into the receive shift register, the data portion of the character transfers to the IRSCDR. The SCI receiver full bit, SCRF, in IRSCI status register 1 (IRSCS1) becomes set, indicating that the received byte can be read. If the SCI receive interrupt enable bit, SCRIE, in IRSCC2 is also set, the SCRF bit generates a receiver CPU interrupt request.

12.5.3.3 Data Sampling

The receiver samples the RxD pin at the RT clock rate. The RT clock is an internal signal with a frequency 16 times the baud rate. To adjust for baud rate mismatch, the RT clock is resynchronized at the following times (see Figure 12-9):

- After every start bit
- After the receiver detects a data bit change from logic 1 to logic 0 (after the majority of data bit samples at RT8, RT9, and RT10 returns a valid logic 1 and the majority of the next RT8, RT9, and RT10 samples returns a valid logic 0)

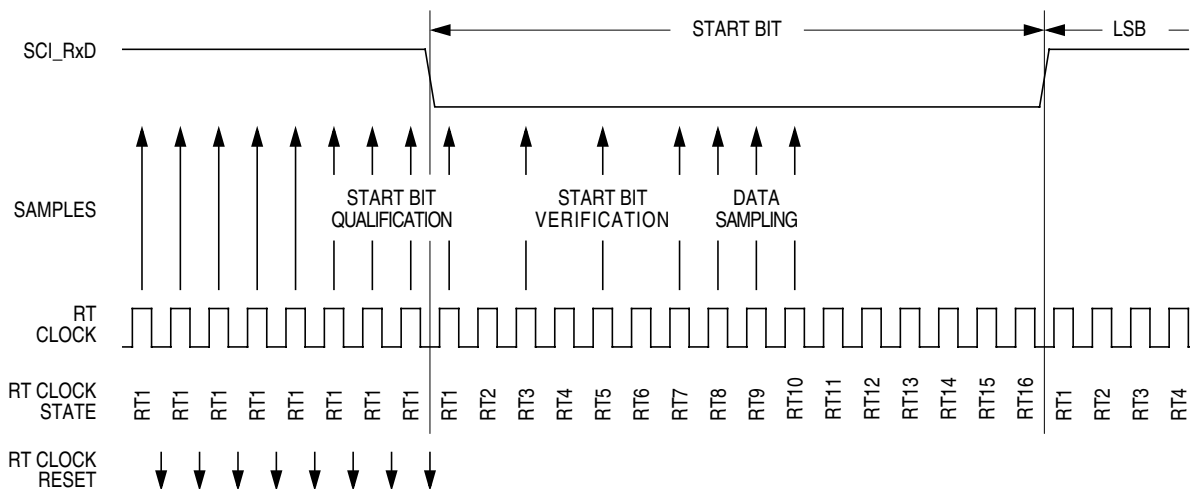


Figure 12-9. Receiver Data Sampling

To locate the start bit, data recovery logic does an asynchronous search for a logic 0 preceded by three logic 1s. When the falling edge of a possible start bit occurs, the RT clock begins to count to 16.

To verify the start bit and to detect noise, data recovery logic takes samples at RT3, RT5, and RT7. Table 12-2 summarizes the results of the start bit verification samples.

Table 12-2. Start Bit Verification

RT3, RT5, and RT7 Samples	Start Bit Verification	Noise Flag
000	Yes	0
001	Yes	1
010	Yes	1

NF — Receiver Noise Flag Bit

This clearable, read-only bit is set when the SCI detects noise on the RxD pin. NF generates an SCI error CPU interrupt request if the NEIE bit in IRSCC3 is also set. Clear the NF bit by reading IRSCS1 and then reading the IRSCDR. Reset clears the NF bit.

- 1 = Noise detected
- 0 = No noise detected

FE — Receiver Framing Error Bit

This clearable, read-only bit is set when a logic 0 is accepted as the stop bit. FE generates an SCI error CPU interrupt request if the FEIE bit in IRSCC3 also is set. Clear the FE bit by reading IRSCS1 with FE set and then reading the IRSCDR. Reset clears the FE bit.

- 1 = Framing error detected
- 0 = No framing error detected

PE — Receiver Parity Error Bit

This clearable, read-only bit is set when the SCI detects a parity error in incoming data. PE generates an SCI error CPU interrupt request if the PEIE bit in IRSCC3 is also set. Clear the PE bit by reading IRSCS1 with PE set and then reading the IRSCDR. Reset clears the PE bit.

- 1 = Parity error detected
- 0 = No parity error detected

12.9.5 IRSCI Status Register 2

IRSCI status register 2 contains flags to signal the following conditions:

- Break character detected
- Incoming data

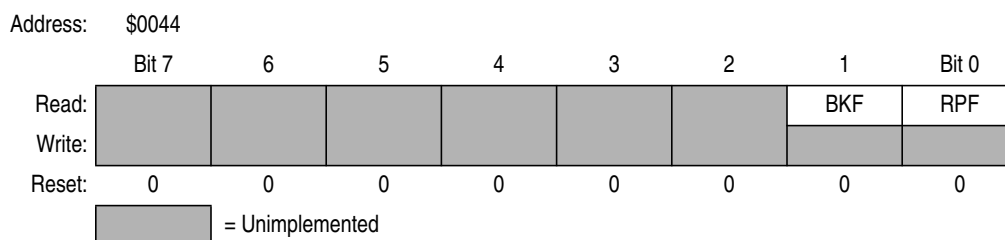


Figure 12-17. IRSCI Status Register 2 (IRSCS2)

BKF — Break Flag Bit

This clearable, read-only bit is set when the SCI detects a break character on the RxD pin. In IRSCS1, the FE and SCRF bits are also set. In 9-bit character transmissions, the R8 bit in IRSCC3 is cleared. BKF does not generate a CPU interrupt request. Clear BKF by reading IRSCS2 with BKF set and then reading the IRSCDR. Once cleared, BKF can become set again only after logic 1s again appear on the RxD pin followed by another break character. Reset clears the BKF bit.

- 1 = Break character detected
- 0 = No break character detected

NOTE

To prevent bus contention with another master SPI after a mode fault error, clear all SPI bits of the data direction register of the shared I/O port before enabling the SPI.

When configured as a slave (SPMSTR = 0), the MODF flag is set if \overline{SS} goes high during a transmission. When CPHA = 0, a transmission begins when \overline{SS} goes low and ends once the incoming SPSCCK goes back to its idle level following the shift of the eighth data bit. When CPHA = 1, the transmission begins when the SPSCCK leaves its idle level and \overline{SS} is already low. The transmission continues until the SPSCCK returns to its idle level following the shift of the last data bit. (See 13.5 Transmission Formats.)

NOTE

Setting the MODF flag does not clear the SPMSTR bit. The SPMSTR bit has no function when SPE = 0. Reading SPMSTR when MODF = 1 shows the difference between a MODF occurring when the SPI is a master and when it is a slave.

When CPHA = 0, a MODF occurs if a slave is selected (\overline{SS} is at logic 0) and later unselected (\overline{SS} is at logic 1) even if no SPSCCK is sent to that slave. This happens because \overline{SS} at logic 0 indicates the start of the transmission (MISO driven out with the value of MSB) for CPHA = 0. When CPHA = 1, a slave can be selected and then later unselected with no transmission occurring. Therefore, MODF does not occur since a transmission was never begun.

In a slave SPI (MSTR = 0), the MODF bit generates an SPI receiver/error CPU interrupt request if the ERRIE bit is set. The MODF bit does not clear the SPE bit or reset the SPI in any way. Software can abort the SPI transmission by clearing the SPE bit of the slave.

NOTE

A logic 1 voltage on the \overline{SS} pin of a slave SPI puts the MISO pin in a high impedance state. Also, the slave SPI ignores all incoming SPSCCK clocks, even if it was already in the middle of a transmission.

To clear the MODF flag, read the SPSCR with the MODF bit set and then write to the SPCR register. This entire clearing mechanism must occur with no MODF condition existing or else the flag is not cleared.

13.8 Interrupts

Four SPI status flags can be enabled to generate CPU interrupt requests.

Table 13-2. SPI Interrupts

Flag	Request
SPTE Transmitter empty	SPI transmitter CPU interrupt request (SPTIE = 1, SPE = 1)
SPRF Receiver full	SPI receiver CPU interrupt request (SPRIE = 1)
OVRF Overflow	SPI receiver/error interrupt request (ERRIE = 1)
MODF Mode fault	SPI receiver/error interrupt request (ERRIE = 1)

Serial Peripheral Interface Module (SPI)

Reading the SPI status and control register with SPRF set and then reading the receive data register clears SPRF. The clearing mechanism for the SPTE flag is always just a write to the transmit data register.

The SPI transmitter interrupt enable bit (SPTIE) enables the SPTE flag to generate transmitter CPU interrupt requests, provided that the SPI is enabled (SPE = 1).

The SPI receiver interrupt enable bit (SPRIE) enables the SPRF bit to generate receiver CPU interrupt requests, regardless of the state of the SPE bit. (See Figure 13-11.)

The error interrupt enable bit (ERRIE) enables both the MODF and OVRF bits to generate a receiver/error CPU interrupt request.

The mode fault enable bit (MODFEN) can prevent the MODF flag from being set so that only the OVRF bit is enabled by the ERRIE bit to generate receiver/error CPU interrupt requests.

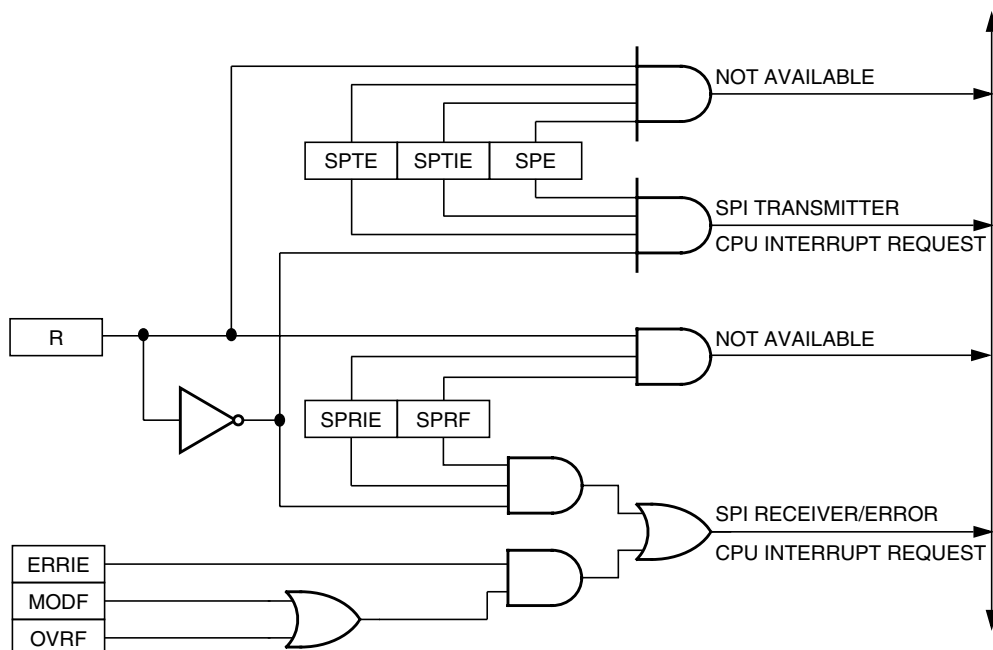


Figure 13-11. SPI Interrupt Request Generation

The following sources in the SPI status and control register can generate CPU interrupt requests:

- SPI receiver full bit (SPRF) — The SPRF bit becomes set every time a byte transfers from the shift register to the receive data register. If the SPI receiver interrupt enable bit, SPRIE, is also set, SPRF generates an SPI receiver/error CPU interrupt request.
- SPI transmitter empty (SPTE) — The SPTE bit becomes set every time a byte transfers from the transmit data register to the shift register. If the SPI transmit interrupt enable bit, SPTIE, is also set, SPTE generates an SPTE CPU interrupt request.

13.9 Resetting the SPI

Any system reset completely resets the SPI. Partial resets occur whenever the SPI enable bit (SPE) is low. Whenever SPE is low, the following occurs:

- The SPTE flag is set.
- Any transmission currently in progress is aborted.

14.6.1 MMIIC Address Register (MMADR)

Address: \$0048

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	MMAD7	MMAD6	MMAD5	MMAD4	MMAD3	MMAD2	MMAD1	MMEXTAD
Write:								
Reset:	1	0	1	0	0	0	0	0

Figure 14-4. MMIIC Address Register (MMADR)

MMAD[7:1] — Multi-Master Address

These seven bits represent the MMIIC interface's own specific slave address when in slave mode, and the calling address when in master mode. Software must update MMAD[7:1] as the calling address while entering master mode and restore its own slave address after master mode is relinquished. This register is cleared as \$A0 upon reset.

MMEXTAD — Multi-Master Expanded Address

This bit is set to expand the address of the MMIIC in slave mode. When set, the MMIIC will acknowledge the following addresses from a calling master: \$MMAD[7:1], 0000000, and 0001 100. Reset clears this bit.

1 = MMIIC responds to the following calling addresses:

\$MMAD[7:1], 0000000, and 0001 100.

0 = MMIIC responds to address \$MMAD[7:1]

For example, when MMADR is configured as:

MMAD7	MMAD6	MMAD5	MMAD4	MMAD3	MMAD2	MMAD1	MMEXTAD
1	1	0	1	0	1	0	1

The MMIIC module will respond to the calling address:

Bit 7	6	5	4	3	2	Bit 1
1	1	0	1	0	1	0

or the general calling address:

0	0	0	0	0	0	0
---	---	---	---	---	---	---

or the calling address:

Bit 7	6	5	4	3	2	Bit 1
0	0	0	1	1	0	0

Note that bit-0 of the 8-bit calling address is the MMRW bit from the calling master.

14.8.4 Write Byte/Word

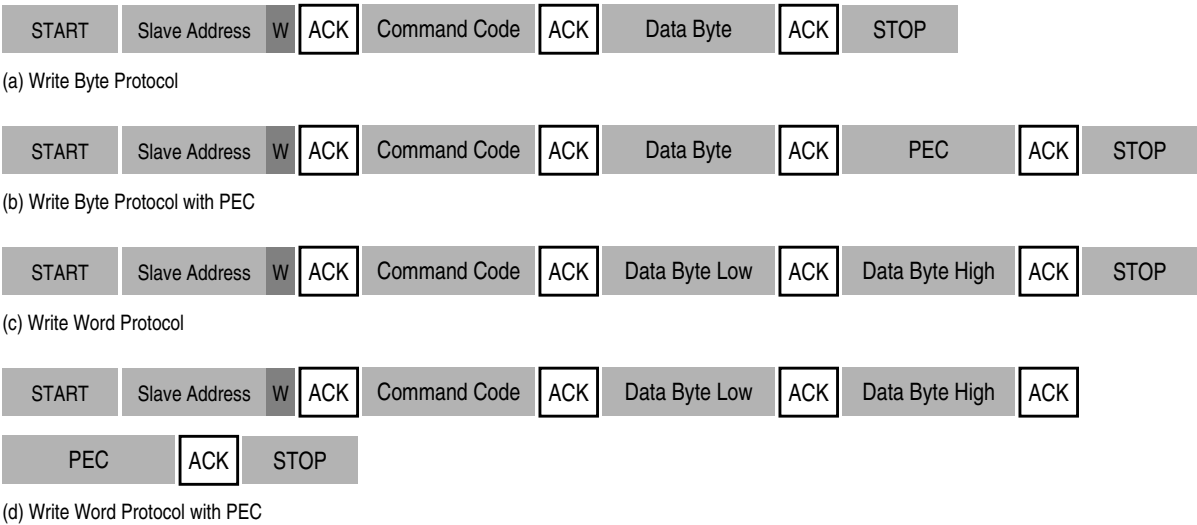


Figure 14-16. Write Byte/Word

14.8.5 Read Byte/Word

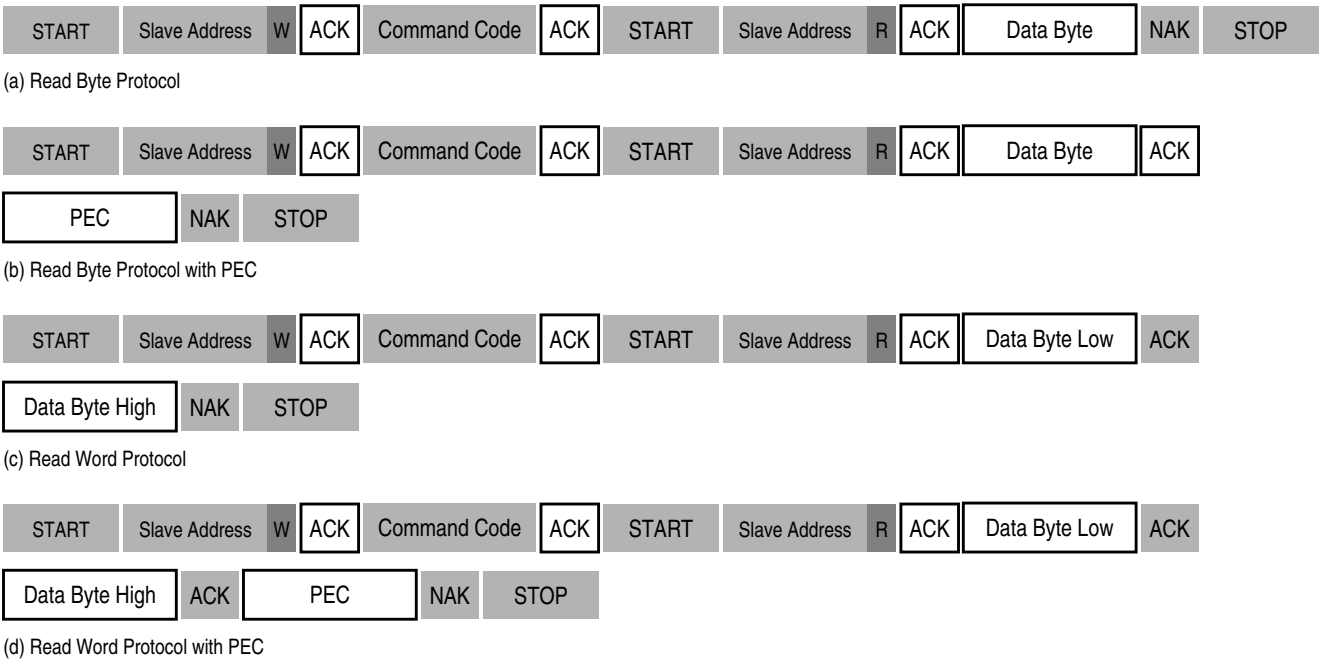


Figure 14-17. Read Byte/Word

Table 15-1. MUX Channel Select

ADCH4	ADCH3	ADCH2	ADCH1	ADCH0	ADC Channel	Input Select
0	0	0	0	0	ADC0	PTA0
0	0	0	0	1	ADC1	PTA1
0	0	0	1	0	ADC2	PTA2
0	0	0	1	1	ADC3	PTA3
0	0	1	0	0	ADC4	PTA4
0	0	1	0	1	ADC5	PTA5
0	0	1	1	0	ADC6	PTA6
0	0	1	1	1	ADC7	PTA7
0 ↓ 1	1 ↓ 1	0 ↓ 1	0 ↓ 0	0 ↓ 0	ADC8 ↓ ADC28	Reserved
1	1	1	0	1	ADC29	V _{REFH} (see Note 2)
1	1	1	1	0	ADC30	V _{REFL} (see Note 2)
1	1	1	1	1	ADC powered-off	—

NOTES:

1. If any unused channels are selected, the resulting ADC conversion will be unknown.
2. The voltage levels supplied from internal reference nodes as specified in the table are used to verify the operation of the ADC converter both in production test and for user applications.

15.7.2 ADC Clock Control Register

The ADC clock control register (ADICLK) selects the clock frequency for the ADC.

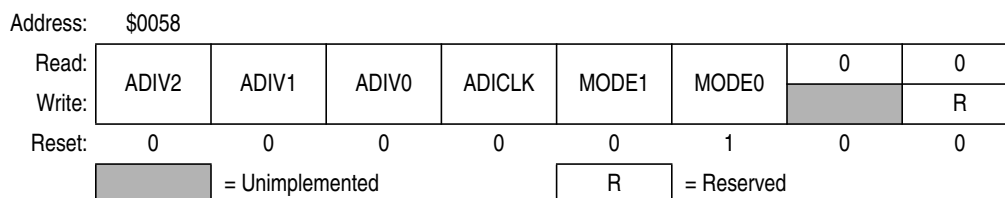


Figure 15-4. ADC Clock Control Register (ADICLK)

ADIV[2:0] — ADC Clock Prescaler Bits

ADIV2, ADIV1, and ADIV0 form a 3-bit field which selects the divide ratio used by the ADC to generate the internal ADC clock.

Table 15-2 shows the available clock configurations. The ADC clock should be set to between 500 kHz and 1MHz.

22.5 5V DC Electrical Characteristics

Table 22-4. DC Electrical Characteristics (5V)

Characteristic ⁽¹⁾	Symbol	Min	Typ ⁽²⁾	Max	Unit
Output high voltage ($I_{LOAD} = -12\text{mA}$) PTA[0:7], PTB[4:7], PTC[0:5], PTD[0:7] ($I_{LOAD} = -15\text{mA}$) PTA[0:7], PTB[4:7], PTC[0:5], PTD[0:7]	V_{OH} V_{OH}	$V_{DD}-0.8$ $V_{DD}-1.0$	— —	— —	V V
Output low voltage ($I_{LOAD} = 6\text{mA}$) PTA[0:7], PTB[4:7], PTC[0:5], PTD[0:7] ($I_{LOAD} = 12\text{mA}$) PTB[0:3], PTC[6:7] ($I_{LOAD} = 15\text{mA}$) PTA[0:7], PTB[4:7], PTC[0:5], PTD[0:7] ($I_{LOAD} = 15\text{mA}$) PTB[0:3], PTC[6:7] ($I_{LOAD} = 15\text{mA}$) as TxD, RxD, SCTxD, SCRxD ($I_{LOAD} = \text{see Table 22-12}$) as SDA, SCL	V_{OL} V_{OL} V_{OL} V_{OL} V_{OLSCI} V_{OLIIIC}	— — — — — —	— — — — — —	0.4 0.4 0.8 0.6 0.4 0.4	V V V V V V
LED sink current ($V_{OL} = 3\text{V}$) PTA[0:7]	I_{OL}	9	15	25	mA
Input high voltage PTA[0:7], PTB[0:7], PTC[0:7], PTD[0:7], \overline{RST} , $\overline{IRQ1}$ OSC1	V_{IH}	$0.7 \times V_{DD}$ $0.7 \times V_{REG}$	— —	V_{DD} V_{REG}	V V
Input low voltage PTA[0:7], PTB[0:7], PTC[0:7], PTD[0:7], \overline{RST} , $\overline{IRQ1}$ OSC1	V_{IL}	V_{SS} V_{SS}	— —	$0.3 \times V_{DD}$ $0.3 \times V_{REG}$	V V
V_{DD} supply current, $f_{OP} = 8\text{MHz}$ Run ⁽³⁾ Wait ⁽⁴⁾ Stop (25°C) with OSC, TBM, and LVI modules on ⁽⁵⁾ with OSC and TBM modules on ⁽⁵⁾ all modules off ⁽⁶⁾ Stop (0 to 85°C) with OSC, TBM, and LVI modules on ⁽⁵⁾ with OSC and TBM modules on ⁽⁵⁾ all modules off ⁽⁶⁾	I_{DD}	— — — — — — —	10 2.5 0.8 22 20 1 45 42	20 10 1.8 150 125 2.5 300 250	mA mA mA μA μA mA μA μA
Digital I/O ports Hi-Z leakage current	I_{IL}	—	—	± 10	μA
Input current	I_{IN}	—	—	± 1	μA
Capacitance Ports (as input or output)	C_{OUT} C_{IN}	— —	— —	12 8	pF pF
POR rearm voltage ⁽⁷⁾	V_{POR}	0	—	100	mV
POR rise time ramp rate ⁽⁸⁾	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage	V_{TST}	$1.4 \times V_{DD}$		8.5	V

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